

Madhavan Swaminathan

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176
papers

1,825
citations

21
h-index

34
g-index

232
ext. papers

2,525
ext. citations

2.1
avg, IF

5.19
L-index

#	Paper	IF	Citations
176	Modeling and transient simulation of planes in electronic packages. <i>IEEE Transactions on Advanced Packaging</i> , 2000 , 23, 340-352		82
175	Electromagnetic Modeling of Through-Silicon Via (TSV) Interconnections Using Cylindrical Modal Basis Functions. <i>IEEE Transactions on Advanced Packaging</i> , 2010 , 33, 804-817		75
174	Electrical modeling of Through Silicon and Package Vias 2009 ,		72
173	Designing and Modeling for Power Integrity. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2010 , 52, 288-310	2	68
172	Rigorous Electrical Modeling of Through Silicon Vias (TSVs) With MOS Capacitance Effects. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2011 , 1, 893-903	1.7	63
171	Electrical-Thermal Co-Simulation of 3D Integrated Systems With Micro-Fluidic Cooling and Joule Heating Effects. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2011 , 1, 234-246	1.7	60
170	High-Dimensional Global Optimization Method for High-Frequency Electronic Design. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2019 , 67, 2128-2142	4.1	55
169	Multilayered Finite-Difference Method (MFDM) for Modeling of Package and Printed Circuit Board Planes. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2007 , 49, 441-447	2	47
168	A Global Bayesian Optimization Algorithm and Its Application to Integrated System Design. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2018 , 26, 792-802	2.6	46
167	Transient Analysis of CMOS-Gate-Driven $\$R_{LGC}\$$ Interconnects Based on FDTD. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2011 , 30, 574-583	2.5	43
166	On-Chip Power-Grid Simulation Using Latency Insertion Method. <i>IEEE Transactions on Circuits and Systems I: Regular Papers</i> , 2008 , 55, 914-931	3.9	41
165	Machine Learning and Uncertainty Quantification for Surrogate Models of Integrated Devices With a Large Number of Parameters. <i>IEEE Access</i> , 2019 , 7, 4056-4066	3.5	41
164	Skin-Effect-Incorporated Transient Simulation Using the Laguerre-FDTD Scheme. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2013 , 61, 4029-4039	4.1	37
163	Application of Machine Learning for Optimization of 3-D Integrated Circuits and Systems. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2017 , 25, 1856-1865	2.6	34
162	A New Self-Healing Methodology for RF Amplifier Circuits Based on Oscillation Principles. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2012 , 20, 1835-1848	2.6	31
161	Transient Analysis of TSV Equivalent Circuit Considering Nonlinear MOS Capacitance Effects. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2015 , 57, 1216-1225	2	30
160	Decoupling Capacitor Placement in Power Delivery Networks Using MFEM. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2011 , 1, 1651-1661	1.7	29

159	A Novel Compact Electromagnetic Bandgap Structure in Power Plane for Wideband Noise Suppression and Low Radiation. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2011 , 53, 996-1004 ²	29
158	Noise Isolation in Mixed-Signal Systems Using Alternating Impedance Electromagnetic Bandgap (AI-EBG) Structure-Based Power Distribution Network (PDN). <i>IEEE Transactions on Advanced Packaging</i> , 2010 , 33, 2-12	28
157	Do we need wide flits in Networks-on-Chip? 2013 ,	21
156	Stopband Analysis Using Dispersion Diagram for Two-Dimensional Electromagnetic Bandgap Structures in Printed Circuit Boards. <i>IEEE Microwave and Wireless Components Letters</i> , 2006 , 16, 645-647 ^{2.6}	21
155	A Laguerre-FDTD Formulation for Frequency-Dependent Dispersive Materials. <i>IEEE Microwave and Wireless Components Letters</i> , 2011 , 21, 225-227	2.6 20
154	Antenna miniaturization using magneto-dielectric substrates 2009 ,	20
153	Electrical-thermal Cosimulation With Nonconformal Domain Decomposition Method for Multiscale 3-D Integrated Systems. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 588-601	1.7 19
152	Inductance and Resistance Calculations in Three-Dimensional Packaging Using Cylindrical Conduction-Mode Basis Functions. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2009 , 28, 846-859	2.5 19
151	Electrical modeling of annular and co-axial TSVs considering MOS capacitance effects 2009 ,	18
150	Air-Gap Transmission Lines on Organic Substrates for Low-Loss Interconnects. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2007 , 55, 1919-1925	4.1 18
149	Surface Roughness Modeling of Substrate Integrated Waveguide in D-Band. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2016 , 64, 1209-1216	4.1 17
148	Coupling analysis of through-silicon via (TSV) arrays in silicon interposers for 3D systems 2011 ,	17
147	Demystifying Machine Learning for Signal and Power Integrity Problems in Packaging. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 1276-1295	1.7 17
146	A novel self-healing methodology for RF Amplifier circuits based on oscillation principles 2009 ,	16
145	Analytical Stability Condition of the Latency Insertion Method for Nonuniform GLC Circuits. <i>IEEE Transactions on Circuits and Systems II: Express Briefs</i> , 2008 , 55, 937-941	3.5 16
144	A Rigorous Model for Through-Silicon Vias With Ohmic Contact in Silicon Interposer. <i>IEEE Microwave and Wireless Components Letters</i> , 2013 , 23, 385-387	2.6 15
143	Constant Current Power Transmission Line-Based Power Delivery Network for Single-Ended Signaling. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2011 , 53, 1050-1064	2 15
142	Electrical-thermal co-analysis for power delivery networks in 3D system integration 2009 ,	15

141	Accurate Transient Simulation of Interconnects Characterized by Band-Limited Data With Propagation Delay Enforcement in a Modified Nodal Analysis Framework. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2008 , 50, 715-729	2	14
140	Achieving near zero SSN power delivery networks by eliminating power planes and using constant current power transmission lines 2009 ,		13
139	Power transmission lines: A new interconnect design to eliminate simultaneous switching noise 2008 ,		13
138	Near-Field and Far-Field Analyses of Alternating Impedance Electromagnetic Bandgap (AI-EBG) Structure for Mixed-Signal Applications. <i>IEEE Transactions on Advanced Packaging</i> , 2007 , 30, 180-190		13
137	Polarization mode basis functions for modeling insulator-coated through-silicon via (TSV) interconnections 2009 ,		12
136	A Bayesian Framework for Optimizing Interconnects in High-Speed Channels 2018 ,		12
135	Design and Characterization of Inductors for Self-Powered IoT Edge Devices. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 1263-1271	1.7	11
134	Modeling of Voltage-Controlled Oscillators Including I/O Behavior Using Augmented Neural Networks. <i>IEEE Access</i> , 2019 , 7, 38973-38982	3.5	10
133	Electrical and thermal modeling of through-silicon via (TSV) arrays in interposer. <i>International Journal of Numerical Modelling: Electronic Networks, Devices and Fields</i> , 2013 , 26, 545-559	1	10
132	. <i>IEEE Transactions on Advanced Packaging</i> , 2009 , 32, 13-25		10
131	Efficient Modeling of Package Power Delivery Networks with Fringing Fields and Gap Coupling in Mixed Signal Systems 2006 ,		10
130	A Passive Equalizer Design for Shielded Differential Through-Silicon Vias in 3-D IC. <i>IEEE Microwave and Wireless Components Letters</i> , 2018 , 28, 768-770	2.6	9
129	Electromagnetic modeling of non-uniform through-silicon via (TSV) interconnections 2012 ,		9
128	Enhancing Signal and Power Integrity Using Double Sided Silicon Interposer. <i>IEEE Microwave and Wireless Components Letters</i> , 2011 , 21, 598-600	2.6	9
127	Causal and Passive Parameterization of S-Parameters Using Neural Networks. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2020 , 68, 4290-4304	4.1	9
126	Transient Simulation of Multiscale Structures Using the Nonconformal Domain Decomposition Laguerre-FDTD Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2015 , 5, 532-540	1.7	8
125	FDFD Modeling of Signal Paths With TSVs in Silicon Interposer. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 708-717	1.7	8
124	Characterization of Next Generation Thin Low-K and Low-Loss Organic Dielectrics From 1 to 110 GHz. <i>IEEE Transactions on Advanced Packaging</i> , 2010 , 33, 180-188		8

123	Polymers for RF Apps. <i>IEEE Microwave Magazine</i> , 2011 , 12, 62-77	1.2	8
122	Conformal Antennas on Liquid Crystalline Polymer Based Rigid-Flex Substrates Integrated With the Front-End Module. <i>IEEE Transactions on Advanced Packaging</i> , 2009 , 32, 797-808		8
121	Design, modeling, and characterization of embedded electromagnetic band gap (EBG) structure 2008 ,		8
120	Broadband and Miniaturized Antenna-in-Package (AiP) Design for 5G Applications. <i>IEEE Antennas and Wireless Propagation Letters</i> , 2020 , 19, 1963-1967	3.8	8
119	Enabling antenna design with nano-magnetic materials using machine learning 2015 ,		7
118	Analysis, Design, and Prototyping of Temperature Resilient Clock Distribution Networks for 3-D ICs. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2015 , 5, 1669-1678	1.7	7
117	Nanomagnetics for High-Performance, Miniaturized Power, and RF Components [Nanopackaging]. <i>IEEE Nanotechnology Magazine</i> , 2012 , 6, 18-23	1.7	7
116	Simulation of power delivery networks with Joule heating effects for 3D integration 2010 ,		7
115	A low cost method for testing integrated RF substrates 2008 ,		7
114	Correlation of PDN impedance with jitter and voltage margin for high speed channels 2008 ,		7
113	Analysis and Design of Electromagnetic Bandgap (EBG) Structures for Power Plane Isolation Using 2D Dispersion Diagrams and Scalability 2006 ,		7
112	Behavioral Modeling of Tunable I/O Drivers With Preemphasis Including Power Supply Noise. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2020 , 28, 233-242	2.6	7
111	Analysis of Parameter Variability in an Integrated Wireless Power Transfer System via Partial Least-Squares Regression. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 1795-1802	1.7	7
110	Architecture, Chip, and Package Codesign Flow for Interposer-Based 2.5-D Chiplet Integration Enabling Heterogeneous IP Reuse. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2020 , 28, 2424-2437	2.6	7
109	A Spectral Convolutional Net for Co-Optimization of Integrated Voltage Regulators and Embedded Inductors 2019 ,		7
108	Bayesian Active Learning for Uncertainty Quantification of High Speed Channel Signaling 2018 ,		7
107	Repeater Insertion to Reduce Delay and Power in Copper and Carbon Nanotube-Based Nanointerconnects. <i>IEEE Access</i> , 2019 , 7, 13622-13633	3.5	6
106	A Hybrid Methodology for Jitter and Eye Estimation in High-Speed Serial Channels Using Polynomial Chaos Surrogate Models. <i>IEEE Access</i> , 2019 , 7, 53629-53640	3.5	6

105	Preconditioned Second-Order Multi-Point Passive Model Reduction for Electromagnetic Simulations. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2010 , 58, 2856-2866	4.1	6
104	DC IR drop solver for large scale 3D power delivery networks 2010 ,		6
103	Filter integration in ultra thin organic substrate via 3D stitched capacitor 2009 ,		6
102	Eye-Pattern Design for High-Speed Differential Links Using Extended Passive Equalization. <i>IEEE Transactions on Advanced Packaging</i> , 2008 , 31, 246-257		6
101	A Heterogeneous Array of Off-Chip Interconnects for Optimum Mechanical and Electrical Performance. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2007 , 129, 460-468	2	6
100	Characterization of Co-Planar Silicon Transmission Lines With and Without Slow-Wave Effect. <i>IEEE Transactions on Advanced Packaging</i> , 2007 , 30, 526-532		6
99	Preliminary application of machine-learning techniques for thermal-electrical parameter optimization in 3-D IC 2016 ,		6
98	Open and Closed Loop Inductors for High-Efficiency System-on-Package Integrated Voltage Regulators 2019 ,		5
97	Constant Voltage-Based Power Delivery Scheme for 3-D ICs and Interposers. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013 , 3, 1907-1916	1.7	5
96	Skin effect modeling of interconnects using the Laguerre-FDTD scheme 2012 ,		5
95	Pseudo-balanced signaling using power transmission lines for parallel links 2011 ,		5
94	Fast EM/Circuit Transient Simulation Using Laguerre Equivalent Circuit (SLeEC). <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2009 , 51, 756-762	2	5
93	Effect of system components on electrical and thermal characteristics for power delivery networks in 3D system integration 2009 ,		5
92	Low-Cost Specification Based Testing of RF Amplifier Circuits using Oscillation Principles. <i>Journal of Electronic Testing: Theory and Applications (JETTA)</i> , 2010 , 26, 13-24	0.7	5
91	Causal Transient Simulation of Passive Networks with Fast Convolution 2006 ,		5
90	Conformal Antennas on Liquid Crystalline Polymer Substrates for Consumer Applications 2007 ,		5
89	Fault Detection and Automated Fault Diagnosis for Embedded Integrated Electrical Passives. <i>Journal of Signal Processing Systems</i> , 1999 , 21, 265-276		5
88	Characterization of ABF/Glass/ABF Substrates for mmWave Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2021 , 11, 384-394	1.7	5

87	Laminated Glass-Based, Compact Inline Stepped-Impedance Resonator Bandpass Filters for 5G New Radio Modules. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2021 , 11, 708-711	1.7	5
86	Modeling and Performance Analysis of Shielded Differential Annular Through-Silicon Via (SD-ATSV) for 3-D ICs. <i>IEEE Access</i> , 2018 , 6, 33238-33250	3.5	5
85	Determining worst-case eye height in low BER channels using Bayesian optimization 2020 ,		4
84	Mechanical and High-Frequency Electrical Study of Printed, Flexible Antenna Under Deformation. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 1088-1100	1.7	4
83	Fast electrical-thermal co-simulation using multigrid method for 3D integration 2012 ,		4
82	New power delivery scheme for 3D ICs to minimize simultaneous switching noise for high speed I/Os 2012 ,		4
81	RF substrates yield improvement using package-chip co-design and on-chip calibration 2010 ,		4
80	Constant current Power Transmission Line based power delivery network for single-ended signaling with reduced simultaneous switching noise 2011 ,		4
79	Extraction of electrical properties of nanomagnetic materials through meander-shaped inductor and inverted-F antenna structures 2012 ,		4
78	Low-Cost One-Port Approach for Testing Integrated RF Substrates 2008 ,		4
77	Dielectric Constant and Loss Tangent Characterization of Thin High-K Dielectrics Using Corner-to-Corner Plane Probing 2006 ,		4
76	Inverse Design of Transmission Lines with Deep Learning 2019 ,		4
75	Impedance Response Extrapolation of Power Delivery Networks using Recurrent Neural Networks 2019 ,		4
74	Preliminary Application of Deep Learning to Design Space Exploration 2018 ,		4
73	A Compact Passive Equalizer Design for Differential Channels in TSV-Based 3-D ICs. <i>IEEE Access</i> , 2018 , 6, 75278-75292	3.5	4
72	Enhancing the Bandwidth of Low-Dropout Regulators Using Power Transmission Lines for High-Speed I/Os. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017 , 7, 533-543	1.7	3
71	Application of a New Power Distribution Scheme for Complex Printed Circuit Boards for High-Speed Signaling. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2015 , 5, 806-817	1.7	3
70	Recent advances in electromagnetic compatibility of 3D-ICs [Part II]. <i>IEEE Electromagnetic Compatibility Magazine</i> , 2016 , 5, 65-74	0.4	3

69	A New Approach for Magneto-Static Hysteresis Behavioral Modeling. <i>IEEE Transactions on Magnetics</i> , 2016 , 52, 1-14	2	3
68	Wireless power transfer integrated board for low power IoT applications 2017 ,		3
67	Characterization of alternate power distribution methods for 3D integration 2014 ,		3
66	System-Level Thermal Modeling Using Nonconformal Domain Decomposition and Model-Order Reduction. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 66-76	1.7	3
65	Consideration of MOS capacitance effect in TSV modeling based on cylindrical modal basis functions 2012 ,		3
64	Design of power delivery networks using power transmission lines and pseudo-balanced signaling for multiple I/Os 2011 ,		3
63	Fast memory-efficient full-wave 3D simulation of power planes 2009 ,		3
62	Low-frequency test method for integrated RF substrates 2009 ,		3
61	A low-cost test method for embedded RF passive circuits using two-tone input signals 2009 ,		3
60	A Survey of Test Techniques for MCM Substrates. <i>Journal of Electronic Testing: Theory and Applications (JETTA)</i> , 1997 , 10, 27-38	0.7	3
59	A low-cost test approach for embedded RF passive circuits 2008 ,		3
58	Compact Electromagnetic Bandgap structure for noise suppression in power plane 2008 ,		3
57	Liquid Crystal Polymer-Based Planar Lumped Component Dual-Band Filters For Dual-Band WLAN Systems 2007 ,		3
56	Electrical Circuit Modeling and Validation of Through-Silicon Vias Embedded in a Silicon Microfluidic Pin-Fin Heat Sink Filled With Deionized Water. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 1337-1347	1.7	3
55	. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2021 , 63, 246-258	2	3
54	High-density low-loss millimeter-wave package interconnects with the impact of dielectric-material surface roughness. <i>Applied Physics Letters</i> , 2021 , 119, 134103	3.4	3
53	Behavioral Modeling of Pre-emphasis Drivers Including Power Supply Noise Using Neural Networks 2019 ,		2
52	Minimizing coupling of power supply noise between digital and RF circuit blocks in mixed signal systems 2014 ,		2

51	Modeling of Power/Ground Planes Using Triangular Elements. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 291-302	1.7	2
50	Pseudo-balanced Signaling Using Power Transmission Lines for Parallel I/O Links. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2013 , 55, 315-327	2	2
49	Implementation of power transmission lines to field programmable gate array ICs for managing signal and power integrity 2013 ,		2
48	An alternate power distribution scheme with superior noise suppression characteristics than EBG 2014 ,		2
47	Timing analysis for thermally robust clock distribution network design for 3D ICs 2013 ,		2
46	Low-Frequency and Low-Cost Test Methodology for Integrated RF Substrates. <i>IEEE Transactions on Advanced Packaging</i> , 2010 , 33, 669-680		2
45	An effective modeling method for multi-scale and multilayered power/ground plane structures 2011 ,		2
44	Low-Noise Power Delivery Network Design Using Power Transmission Line for Mixed-Signal Testing 2011 ,		2
43	Near zero SSN power delivery networks using Constant Voltage Power Transmission Lines 2009 ,		2
42	Chip-package co-simulation with multiscale structures 2008 ,		2
41	2008 IEEE electrical performance of electronic packaging suppression of vertical coupling using Electromagnetic Band Gap structures 2008 ,		2
40	Analysis for Signal and Power Integrity Using the Multilayered Finite Difference Method 2007 ,		2
39	Frequency-Dependent Dielectric Constant and Loss Tangent Characterization of Thin Dielectrics Using a Rapid Solver 2007 ,		2
38	Cylindrical Conduction Mode Basis Functions for Modeling of Inductive Couplings in System-in-Package (SiP) 2007 ,		2
37	Eye-Pattern Improvement for Design of High-Speed Differential Links Using Passive Equalization 2006 ,		2
36	Extraction of S-Parameters from TDR/TDT Measurements using Rational Functions 2000 ,		2
35	A Non-Random Exploration based Method for the optimization of Capacitors in Power Delivery Networks 2020 ,		2
34	Design Flow for Active Interposer-Based 2.5-D ICs and Study of RISC-V Architecture With Secure NoC. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 2047-2060	1.7	2

33	Design Space Extrapolation for Power Delivery Networks using a Transposed Convolutional Net 2021 ,		2
32	16-4: Invited Paper: Process Design Kit and Design Automation for Flexible Hybrid Electronics. <i>Digest of Technical Papers SID International Symposium</i> , 2019 , 50, 217-220	0.5	1
31	FDFD Nonconformal Domain Decomposition Method for the Electromagnetic Modeling of Interconnections in Silicon Interposer. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2015 , 57, 496-504		1
30	Reverse Power Delivery Network for Wireless Power Transfer. <i>IEEE Microwave and Wireless Components Letters</i> , 2018 , 28, 624-626	2.6	1
29	One-Port Resonance-Based Test Technique for RF Interconnect and Filters Embedded in RF Substrates. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013 , 3, 236-246 ^{1.7}		1
28	A Simple Technique for Power Distribution With Better Characteristics Than Electromagnetic Bandgap Structures. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2015 , 5, 797-805	1.7	1
27	Suppression of Vertical Electromagnetic Coupling in Multilayer Packages. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012 , 2, 418-429	1.7	1
26	Memory efficient Laguerre-FDTD scheme for dispersive media 2013 ,		1
25	Simple Equivalent Circuit Model of a Stripline in Inhomogeneous Dielectric Media. <i>IEEE Microwave and Wireless Components Letters</i> , 2009 , 19, 771-773	2.6	1
24	Conformal WLAN/WiMAX antenna on rigid-flex liquid crystalline polymer based substrate 2009 ,		1
23	Analysis of frequency-dependent lossy transmission lines driven by CMOS gates 2009 ,		1
22	Extraction of material properties for low-K and low-loss dielectrics using cavity resonator and efficient finite difference solver up to 40GHz 2008 ,		1
21	A low-cost approach for testing embedded rf passive circuits based on oscillation principle 2008 ,		1
20	Multi-layer fringe-field augmentations for the efficient modeling of package power planes 2008 ,		1
19	Wideband electrical modeling of large three-dimensional interconnects using accelerated generation of partial impedances with cylindrical conduction mode basis functions 2008 ,		1
18	Design of Integrated RF Modules with Process Control Monitors on Liquid Crystalline Polymer Substrates for Large Volume Manufacturing 2007 ,		1
17	Efficient Simulation of Power/Ground Planes for SiP Applications 2007 ,		1
16	Broadband Modeling and Tuning of Multi-layer RF Circuits using Physical Augmentation Methodology 2007 ,		1

15	A survey of various computer architectures for solution of large matrix equations. <i>International Journal of Numerical Modelling: Electronic Networks, Devices and Fields</i> , 1995 , 8, 153-168	1	1
14	Waveguide mode solution using a hybrid edge element approach. <i>The International Executive</i> , 1995 , 5, 122-130		1
13	Automated I/O Library Generation for Interposer-Based System-in-Package Integration of Multiple Heterogeneous Dies. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 111-122	1.7	1
12	Computation of Maximum Voltage Droop in Power Delivery Networks. <i>IEEE Access</i> , 2020 , 8, 197875-197884	3.4	1
11	Augmented finite element method (AFEM) for the linear steady-state thermal and thermomechanical analysis of heterogeneous integration architectures 2021 ,		1
10	Combined integral equation based circuit modeling of interconnections in electronic packaging 2016 ,		1
9	Chiplet/Interposer Co-Design for Power Delivery Network Optimization in Heterogeneous 2.5D ICs. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2021 , 1-1	1.7	1
8	Process design kit and design automation for flexible hybrid electronics. <i>Journal of the Society for Information Display</i> , 2020 , 28, 241-251	2.1	0
7	Machine Learning-Based System Optimization and Uncertainty Quantification for Integrated Systems 2019 , 505-536		
6	A Bit-Time-Dependent Model of I/O Drivers for Overclocking Analysis. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2020 , 28, 1630-1637	2.6	
5	An Inductive Voltage Regulator With Overdrive Tracking Across Input Voltage in Cascoded Power Stage. <i>IEEE Transactions on Circuits and Systems II: Express Briefs</i> , 2020 , 67, 3083-3087	3.5	
4	Extraction of S-parameters from time domain reflectometry and transmission measurements using rational functions. <i>International Journal of RF and Microwave Computer-Aided Engineering</i> , 2003 , 13, 74-85	1.5	
3	HilbertNet: A Probabilistic Machine Learning Framework for Frequency Response Extrapolation of Electromagnetic Structures. <i>IEEE Transactions on Electromagnetic Compatibility</i> , 2021 , 1-13	2	
2	Multiphysics Challenges and Opportunities for Integrated Voltage Regulators in Power Delivery Architectures. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2021 , 1-1	1.7	
1	Clock Delivery Network Design and Analysis for Interposer-Based 2.5-D Heterogeneous Systems. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , 2021 , 29, 605-616	2.6	